METHOD FOR MANUFACTURING SPACE TRANSFORMER BY USING CARRIER SUBSTRATE MADE FOR CHIP PACKAGE AND PROVIDED WITH ELONGATED CONTACTS

ABSTRACT

A method of manufacturing a space transformer includes providing a carrier substrate made for a chip package, forming an insulated layer disposed on the carrier substrate, and forming a conductive block. The carrier substrate is formed with elongated first and second wires. The first wire has an elongated contact which is longer than the width of the first wire. The insulated layer is formed with a hole corresponding in position to the elongated contact. The conductive block is formed with an elongated connecting column located in the hole and connected with the elongated contact, and a cylindrical contact pad exposed at the outside of the insulated layer, larger-sized than the elongated connecting column is connected with the elongated connecting column. As a result, the cylindrical contact pad has sufficient area and structural strength for contact with a probe needle.

Figure 1